

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	siemitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 14:39
S2	13307	seimitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S3	7	laser and tape and dicing and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 11:59
S4	1191	laser and tape and dicing and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:27
S5	304	street and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:59
S6	54	yag and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:59
S7	15	("5552345").URPN.	USPAT	OR	ON	2005/03/14 09:05
S8	9	("4543464" "4716270" "4861964" "4865686" "5151389" "5185295" "5552345" "5922224" "6257224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 09:08
S9	2	("6737606").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 10:12

S10	11	("4355457" "4610079" "5091331" "5302554" "5356081" "5543365" "5552345" "5902499" "5904546" "6427676" "6555294").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:13
S11	13	("5543365").URPN.	USPAT	OR	ON	2005/08/16 10:14
S12	9	("20010040152" "20020115235" "4610079" "5543365" "6211488" "6252197" "6271102" "6407360" "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:19
S13	22	("4015175" "4104697" "4292576" "4312115" "4721977" "4729971" "4814296" "4846032" "4900283" "4985982" "5000811" "5217907" "5219796" "5272114" "5369060" "5477065" "5786266" "5843831" "5858808" "5943591" "5998238" "6124148").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:22
S14	2	("6734083").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 11:57
S15	0	("6734083").URPN.	USPAT	OR	ON	2005/08/16 11:57
S16	9	("20010040152" "20020115235" "4610079" "5543365" "6211488" "6252197" "6271102" "6407360" "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 11:57
S17	7524	laser and (cutting adj wheel or dicing) and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:00
S18	3528	(tape or adhesive) and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:00

S19	690	melt and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:01
S20	155	street and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:09
S21	846	(438/460).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 12:09
S22	308	laser and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:09
S23	11	("2911773" "3081586" "3852876" "3970819" "3991296" "4019248" "4135291" "4217689" "4237601").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 12:31
S24	20	("4355457").URPN.	USPAT	OR	ON	2005/08/16 12:32
S25	36	("4610079").URPN.	USPAT	OR	ON	2005/08/16 12:34
S26	7	("5785796").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 14:39
S27	9	("20010040152" "20020115235" "4610079" "5543365" "6211488" "6252197" "6271102" "6407360" "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/02 08:11
S28	36	("4610079").URPN.	USPAT	OR	ON	2006/01/02 08:12
S29	47	("4814296").URPN.	USPAT	OR	ON	2006/01/02 08:14

S30	44	("20020086459" "20020089054" "20020125557" "3838501" "4015175" "4104697" "4249299" "4292576" "4312115" "4670770" "4721977" "4729971" "4814296" "4837184" "4846032" "4900283" "4949148" "4985982" "4992847" "4996587" "5000811" "5019943" "5095360" "5160403" "5216278" "5217907" "5219796" "5272114" "5369060" "5477065" "5706176" "5786266" "5804004" "5814885" "5843831" "5858808" "5904548" "5922224" "5943591" "5998238" "6049124" "6055976" "6252302" "6265119").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/02 08:27
S31	1383	(combined or combination) and saw and dicing and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:25
S32	180	((melt or melted or melting) and (saw or sawing or cut or cutting) and (wafer or substrate) and semiconductor).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:24
S33	4	laser near4 dicing adj tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:26
S34	14145	seimitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S35	78856	laser and cutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28

S36	5307	dicing and tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S37	1130	S35 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S38	902	semiconductor and S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S39	387	(melt or melting or melted) and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:29